

Vishay Siliconix

COMPLIANT

# N-Channel 20-V (D-S) 175 °C MOSFET

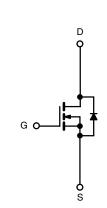
| PRODUCT SUMMARY          |                                   |                                 |  |
|--------------------------|-----------------------------------|---------------------------------|--|
| V <sub>(BR)DSS</sub> (V) | r <sub>DS(on)</sub> (Ω)           | I <sub>D</sub> (A) <sup>a</sup> |  |
| 20                       | 0.0045 at V <sub>GS</sub> = 10 V  | 60                              |  |
|                          | 0.0065 at V <sub>GS</sub> = 4.5 V | 60                              |  |

#### **FEATURES**

- TrenchFET<sup>®</sup> Power MOSFET
- 175 °C Junction Temperature
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested

#### **APPLICATIONS**

• OR-ing



N-Channel MOSFET

GDS

DRAIN connected to TAB

Top View

Ordering Information: SUP60N02-4m5P-E3 (Lead (Pb)-free)

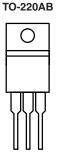
| <b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25 \text{ °C}$ , unless otherwise noted |                                     |                                   |                  |      |  |
|--|-------------------------------------|-----------------------------------|------------------|------|--|
| Parameter  |                                     | Symbol                            | Limit            | Unit |  |
| Drain-Source Voltage   |                                     | V <sub>DS</sub>                   | 20               | V    |  |
| Gate-Source Voltage  |                                     | V <sub>GS</sub>                   | ± 20             |      |  |
| Continuous Drain Current ( $T_J = 175 \ ^{\circ}C$ )                           | T <sub>C</sub> = 25 °C              | 1-                                | 60 <sup>a</sup>  | A    |  |
|  | T <sub>C</sub> = 100 °C             | I <sub>D</sub>                    | 60 <sup>a</sup>  |      |  |
| Pulsed Drain Current   |                                     | I <sub>DM</sub>                   | 120              | 1    |  |
| Single Pulse Avalanche Current   | L = 0.1 mH                          | I <sub>AS</sub>                   | 50               |      |  |
| Single Pulse Avalanche Energy  |                                     | E <sub>AS</sub>                   | 125              | mJ   |  |
| Maximum Power Dissipation <sup>b</sup>   | T <sub>C</sub> = 25 °C              | – P <sub>D</sub>                  | 120 <sup>c</sup> | w    |  |
|  | T <sub>A</sub> = 25 °C <sup>d</sup> | ГD                                | 3.75             |      |  |
| Operating Junction and Storage Temperature Range                               |                                     | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 175      | °C   |  |

| THERMAL RESISTANCE RATINGS                   |                   |       |      |
|--|-------------------|-------|------|
| Parameter                                    | Symbol            | Limit | Unit |
| Junction-to-Ambient (PCB Mount) <sup>d</sup> | R <sub>thJA</sub> | 40    | °C/W |
| Junction-to-Case                             | R <sub>thJC</sub> | 1.25  | 0/11 |

Notes:

a. Package limited.

a. Fuddage immediate 1%.
b. Duty cycle ≤ 1%.
c. See SOA curve for voltage derating.
d. When mounted on 1" square PCB (FR-4 material).



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# SUP60N02-4m5P

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| Parameter                                     | Symbol               | Test Conditions   | Min. | Тур.   | Max.   | Unit |
|---|----------------------|---|------|--------|--------|------|
| Static  |                      |   |      |        |        |      |
| Drain-Source Breakdown Voltage                | V <sub>(BR)DSS</sub> | $V_{DS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$   | 20   |        |        | v    |
| Gate-Threshold Voltage                        | V <sub>GS(th)</sub>  | $V_{DS} = V_{GS}, I_D = 250 \ \mu A$  | 1.0  |        | 3      |      |
| Gate-Body Leakage                             | I <sub>GSS</sub>     | $V_{DS} = 0 V, V_{GS} = \pm 20 V$   |      |        | ± 100  | nA   |
| Zero Gate Voltage Drain Current               |                      | $V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$   |      |        | 1      | μΑ   |
|   | I <sub>DSS</sub>     | $V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$   |      |        | 50     |      |
|   |                      | $V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$   |      |        | 250    |      |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>   | $V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$   | 100  |        |        | Α    |
| Drain-Source On-State Resistance <sup>a</sup> |                      | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A   |      | 0.0036 | 0.0045 | - Ω  |
|   |                      | $V_{GS}$ = 10 V, $I_{D}$ = 20 A, $T_{J}$ = 125 °C   |      |        | 0.0068 |      |
|   | r <sub>DS(on)</sub>  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C  |      |        | 0.008  |      |
|   |                      | V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 20 A  |      | 0.0052 | 0.0065 |      |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>      | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 20 A   |      | 95     |        | S    |
| Dynamic <sup>b</sup>                          |                      |   | J    |        |        |      |
| Input Capacitance                             | C <sub>iss</sub>     |   |      | 5950   |        | pF   |
| Output Capacitance                            | C <sub>oss</sub>     | $V_{GS}$ = 0 V, $V_{DS}$ = 10 V, f = 1 MHz  |      | 985    |        |      |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>     |   |      | 365    |        |      |
| Total Gate Charge <sup>b</sup>                | Qg                   |   |      | 33     | 50     | nC   |
| Gate-Source Charge <sup>b</sup>               | Q <sub>gs</sub>      | $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 50 \text{ A}$   |      | 18     |        |      |
| Gate-Drain Charge <sup>b</sup>                | Q <sub>gd</sub>      |   |      | 7      |        |      |
| Gate Resistance                               | R <sub>g</sub>       |   | 0.75 | 1.5    | 2.3    | Ω    |
| Turn-On Delay Time <sup>b</sup>               | t <sub>d(on)</sub>   |   |      | 15     | 25     |      |
| Rise Time <sup>b</sup>                        | t <sub>r</sub>       | $V_{DD}$ = 10 V, R <sub>L</sub> = 0.2 $\Omega$<br>I <sub>D</sub> $\cong$ 50 A, V <sub>GEN</sub> = 10 V, R <sub>g</sub> = 1.0 $\Omega$ |      | 7      | 11     | ns   |
| Turn-Off Delay Time <sup>b</sup>              | t <sub>d(off)</sub>  |   |      | 35     | 55     |      |
| Fall Time <sup>b</sup>                        | t <sub>f</sub>       |   |      | 8      | 12     |      |
| Source-Drain Diode Ratings and Cha            | racteristics T       | $C = 25 \ ^{\circ}C^{c}$  |      | •      |        |      |
| Continuous Current                            | ۱ <sub>S</sub>       |   |      |        | 60     | A    |
| Pulsed Current                                | I <sub>SM</sub>      |   |      | 1      | 100    |      |
| Forward Voltage <sup>a</sup>                  | V <sub>SD</sub>      | $I_{F} = 20 \text{ A}, V_{GS} = 0 \text{ V}$  |      | 0.85   | 1.5    | V    |
| Reverse Recovery Time                         | t <sub>rr</sub>      |   |      | 45     | 90     | ns   |
| Peak Reverse Recovery Current                 | I <sub>RM</sub>      | I <sub>F</sub> = 20 A, di/dt = 100 A/μs   |      | 1.7    | 3.4    | Α    |
| Reverse Recovery Charge                       | Q <sub>rr</sub>      |   |      | 0.039  | 0.155  | μC   |

Notes:

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %

b. Independent of operating temperature.

c. Guaranteed by design, not subject to production testing.

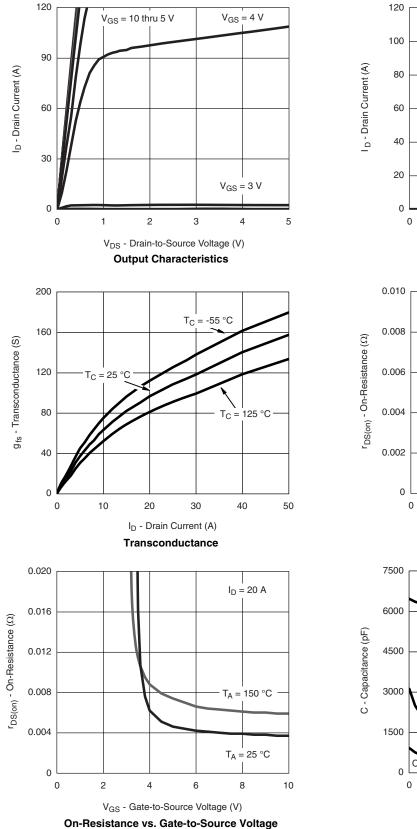
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

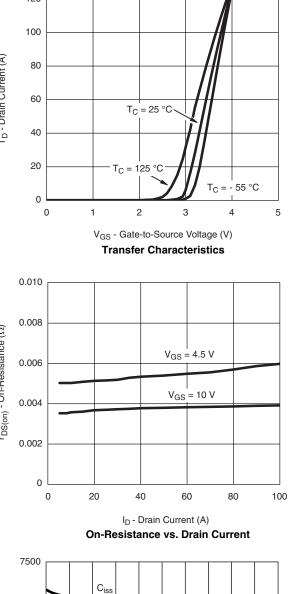


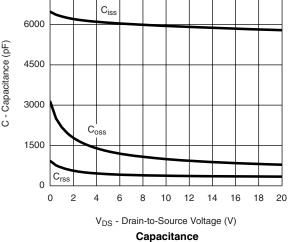
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### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

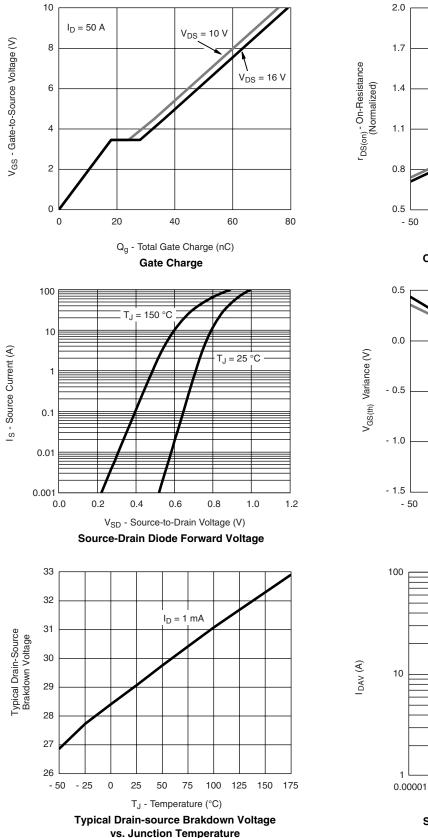


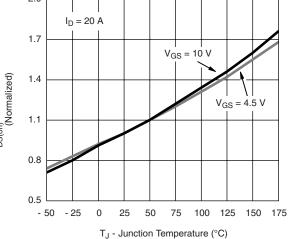




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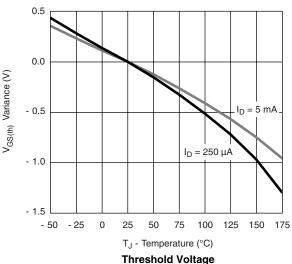
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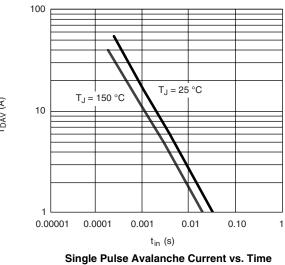


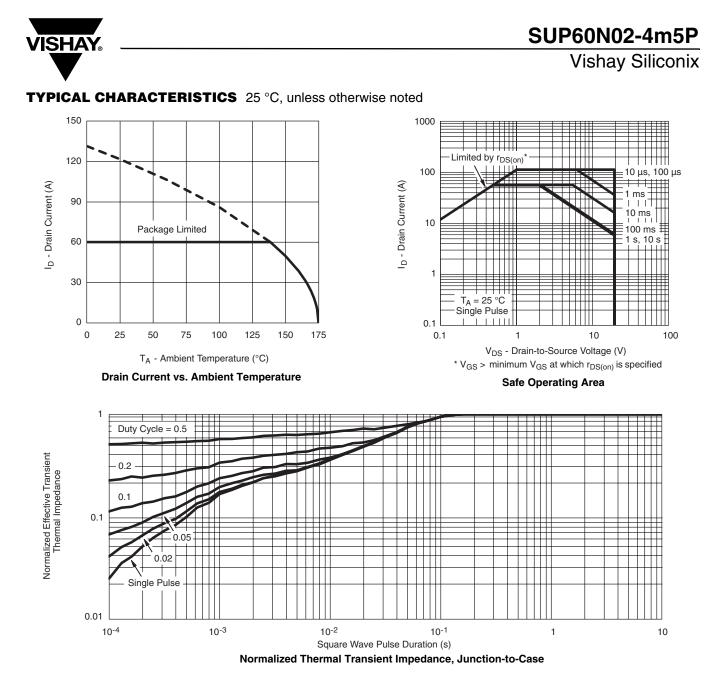


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On-Resistance vs. Junction Temperature







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